



Complementary 20 V (D-S) Low-Threshold MOSFET

PRODUCT SUMMARY						
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)			
		0.280 at V _{GS} = 4.5 V	1.28			
N-Channel	20	0.360 at V _{GS} = 2.5 V	1.13			
		0.450 at V _{GS} = 1.8 V	1.00			
P-Channel	- 20	0.490 at V _{GS} = - 4.5 V	- 1.00			
		0.750 at V _{GS} = - 2.5 V	- 0.81			
		1.10 at V _{GS} = - 1.8 V	- 0.67			

FEATURES

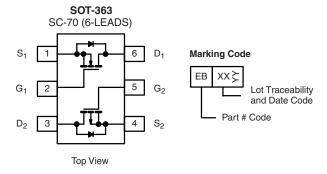
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFETs: 1.8 V Rated
- Thermally Enhanced SC-70 Package
- · Fast Switching
- Compliant to RoHS Directive 2002/95/EC





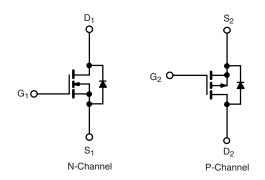
APPLICATIONS

· Load Switch for Portable Devices



Ordering Information: Si1563DH-T1-E3 (Lead (Pb)-free)

Si1563DH-T1-GE3 (Lead (Pb)-free and Halogen-free)



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted								
			N-Channel		P-Channel			
Parameter		Symbol	5 s	Steady State	5 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	20		- 20		V	
Gate-Source Voltage		V_{GS}	± 8		± 8		V	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 25 °C	- I _D	1.28	1.13	- 1.00	- 0.88	А	
	T _A = 85 °C		0.92	0.81	- 0.72	- 0.63		
Pulsed Drain Current		I _{DM}	4.0		- 3.0			
Continuous Source Current (Diode Conduction) ^a		I _S	0.61	0.48	- 0.61	- 0.48		
Maximum Power Dissipation ^a	T _A = 25 °C	В	0.74	0.57	0.30	0.57	W	
	T _A = 85 °C	P _D	0.38	0.30	0.16	0.3		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^a	t ≤ 5 s	- R _{thJA}	130	170			
	Steady State		170	220	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	80	100			

Notes:

a. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static		,				l		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 100 \mu A$	N-Ch	0.45		1		
		V _{DS} = V _{GS} , I _D = - 100 μA	P-Ch	- 0.45		1	V	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V	N-Ch			± 100	nA	
			P-Ch			± 100		
Zero Gate Voltage Drain Current		V _{DS} = 16 V, V _{GS} = 0 V	N-Ch			1		
		V _{DS} = - 16 V, V _{GS} = 0 V				- 1		
	I _{DSS}	V _{DS} = 16 V, V _{GS} = 0 V, T _J = 85 °C	N-Ch			5	μΑ	
		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	P-Ch			- 5	- 5	
On-State Drain Current ^a		$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	2			А	
	I _{D(on)}	$V_{DS} \le$ - 5 V, $V_{GS} =$ - 4.5 V	P-Ch	- 2				
		$V_{GS} = 4.5 \text{ V}, I_D = 1.13 \text{ A}$	N-Ch		0.220	0.280		
		$V_{GS} = -4.5 \text{ V}, I_D = -0.88 \text{ A}$	P-Ch		0.400	0.490		
Drain-Source On-State Resistance ^a	B	$V_{GS} = 2.5 \text{ V}, I_D = 0.99 \text{ A}$	N-Ch		0.281 0.360	Ω		
Diain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, I_D = -0.71 \text{ A}$	P-Ch		0.610	0.750	52	
		$V_{GS} = 1.8 \text{ V}, I_D = 0.20 \text{ A}$	N-Ch		0.344	0.450		
		$V_{GS} = -1.8 \text{ V}, I_D = -0.20 \text{ A}$	P-Ch		0.850	1.10		
Forward Transconductance ^a	9fs	$V_{DS} = 10 \text{ V}, I_{D} = 1.13 \text{ A}$	N-Ch		2.6		s	
		$V_{DS} = -10 \text{ V}, I_{D} = -0.88 \text{ A}$	P-Ch	P-Ch 1.5			3	
Diode Forward Voltage ^a	V _{SD}	I _S = 0.48 A, V _{GS} = 0 V	N-Ch		0.8	1.2	V	
		$I_S = -0.48 \text{ A}, V_{GS} = 0 \text{ V}$	P-Ch		- 0.8	- 1.2	V	
Dynamic ^b								
Total Gate Charge	Qg	N. Channel	N-Ch		1.25	2	nC	
Total Gate Charge		N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1.13 \text{ A}$	P-Ch		1.2	1.8		
Gate-Source Charge	Q _{gs}		N-Ch		0.21			
date course charge	⊶gs	P-Channel	P-Ch		0.3			
Gate-Drain Charge	Q _{gd}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.88$	N-Ch		0.3			
			P-Ch		0.21			
Turn-On Delay Time	t _{d(on)}		N-Ch		15	25		
		N-Channel	P-Ch		18	30	ns	
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_L = 20 \Omega$	N-Ch		22	35		
		$I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$	P-Ch		25	40		
Turn-Off Delay Time	t _{d(off)}	P-Channel	N-Ch		25	40		
		$V_{DD} = -10 \text{ V}, R_L = 20 \Omega$	P-Ch		15	25		
Fall Time	t _f	$I_D \cong$ - 0.5 A, V_{GEN} = - 4.5 V, R_g = 6 Ω	N-Ch		12	20		
	4		P-Ch		12	20		
Reverse Recovery Time	t _{rr}	I _F = 0.48 A, dl/dt = 100 A/μs	N-Ch	_	30	60		
Heverse necovery Tille		i _F = 0.46 A, αί/αι = 100 A/μS	P-Ch		30	60		

Notes:

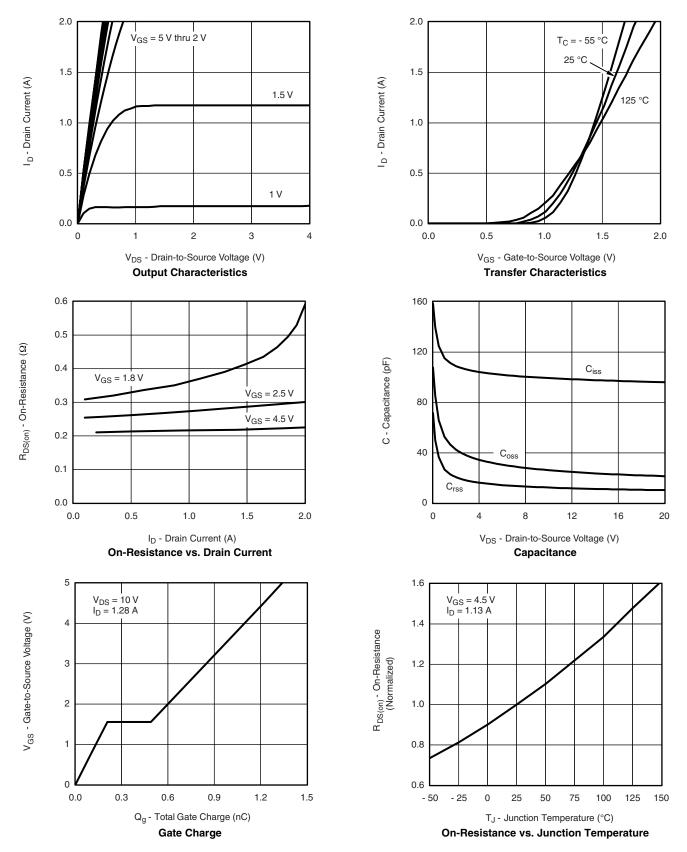
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



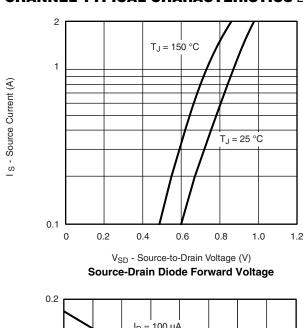


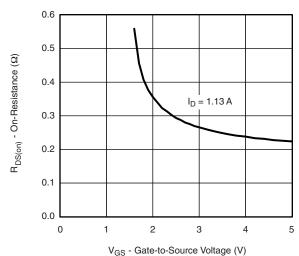
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



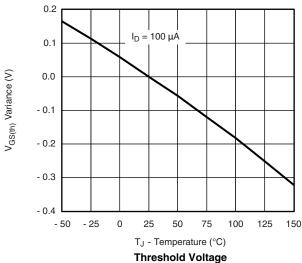
VISHAY

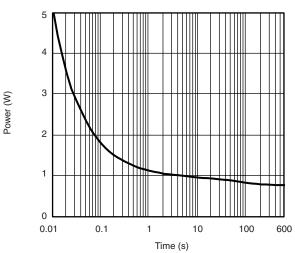
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



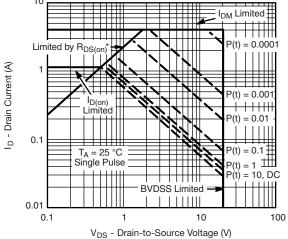








Single Pulse Power, Junction-to-Ambient

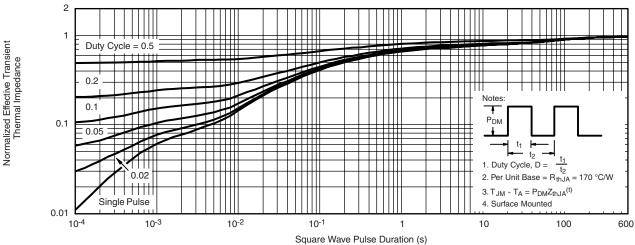


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

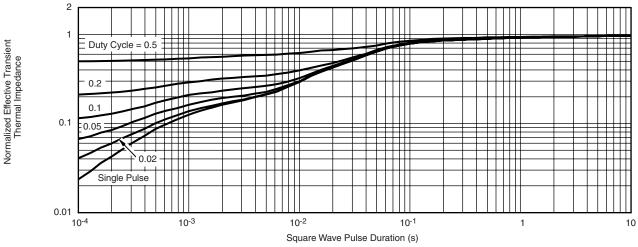
Safe Operating Area, Junction-to-Ambient



N-CHANNEL TYPICAL CHARACTERISTICS 25 $^{\circ}$ C, unless otherwise noted



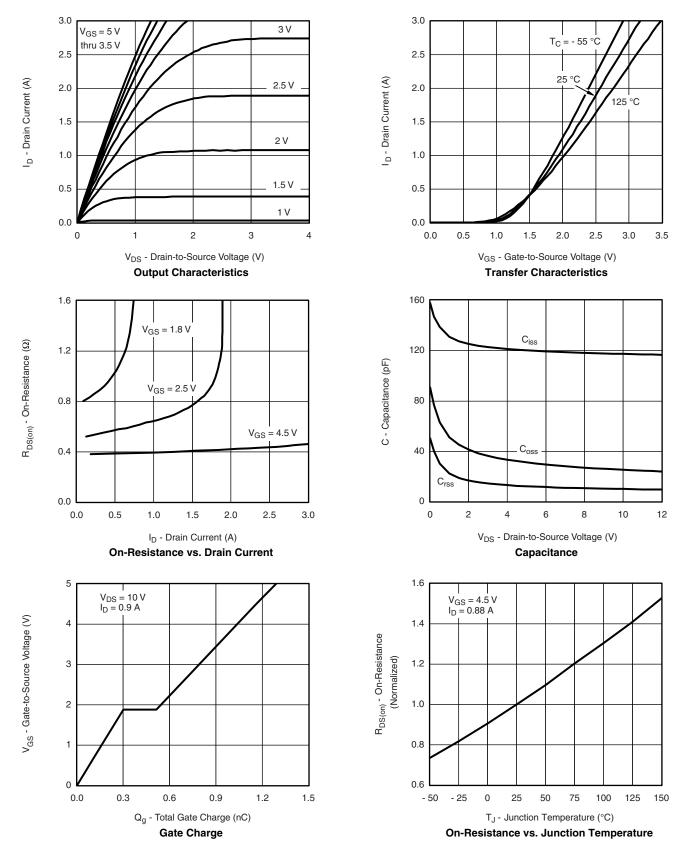
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



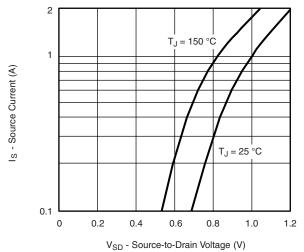
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



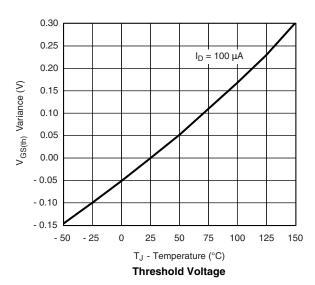




P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

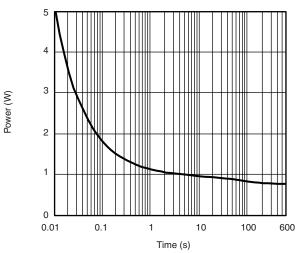


Source-Drain Diode Forward Voltage

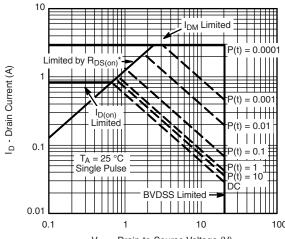


V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



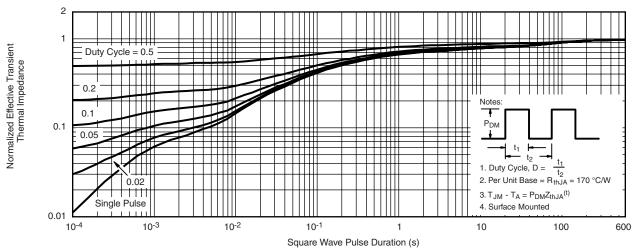
V_{DS} - Drain-to-Source Voltage (V)

Safe Operating Area, Junction-to-Ambient

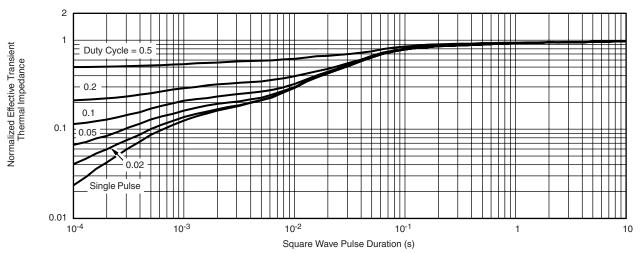
 $^{^{\}star}$ V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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